

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJQ13P04
Package Type :	SOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	11.5407%
Lead Frame	Cu	7440-50-8	97.7175%	11.7013%
	Fe	7439-89-6	2.10%	
	P	7723-14-0	0.012%	
	Zn	7440-66-6	0.12%	
	Copper Coat	7440-50-8	0.025%	
	Silver Coat	7440-50-8	0.025%	
	Pb	7439-92-1	0.0005%	
Die Attach Material	Silver	7440-22-4	80.00%	0.129%
	Reaction product: bisphenol-F-(epichlorhydrin); epoxy resin	9003-36-5	11.00%	
	1,4-bis(2,3 epoxypropoxy)butane	2425-79-8	8.00%	
	dapsone	80-08-0	1.00%	
Wire	Copper	7440-50-8	99.996%	0.0316%
	Other	/	0.004%	
Mold compound	Epoxy Resin.1	Trade Secret	0.50%	76.0522%
	Epoxy Resin.2	Trade Secret	2.00%	
	Phenolic resin	Trade Secret	5.00%	
	Organophosphorus compounds	60676-86-0	1.00%	
	Amorphous silica1	1333-86-4	81.20%	
	Amorphous silica2	60676-86-0	10.00%	
	Carbon Black	1333-86-4	0.30%	
Plating	Sn	7440-31-5	99.99%	0.5452%
	Others	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.